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Deborah W. Wenocur

#17
no
3/31/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: K. Sahota, D. Schonauer, J. Groschopf,)
G. Marxsen, and S. Avanzino,) Grp Art Unit: 1765
Assignee: Advanced Micro Devices, Inc.) Exam: L. Umez Eronini
Serial Number: 09/749,191)
Filed: December 26, 2000)
For: PREVENTION OF PRECIPITATION)
DEFECTS ON COPPER INTER-)
CONNECTS DURING CMP BY USE)
OF SOLUTIONS CONTAINING)
ORGANIC COMPOUNDS WITH)
SILICA ADSORPTION AND COPPER)
CORROSION INHIBITING)
PROPERTIES)

Assistant Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir,

This is in response to the Office Action mailed on December 19, 2002.

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